

Abstract

There is provided a method for partially plating on a base of synthetic resins or other materials including not only a single base but an assembly thereof comprising a number of chip bases for producing electronic and electric parts such as printed circuit board, lead frame insert molded circuit parts, etc. A method for partially plating on an assembly of bases 21 by the use of a plating catalyst comprising a coating process to coat a surface to be plated or not to be plated by means of a coating material selected from a water soluble polymer or hydrolyzable polymer either before or after a catalyst applying process to soak a container containing bases 21 in a plating catalyst bath.

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